

Title (en)
Hybrid integrated circuit device.

Title (de)
Hybridschaltungsanordnung.

Title (fr)
Dispositif à circuit intégré hybride.

Publication
EP 0665560 A2 19950802 (DE)

Application
EP 94119166 A 19941205

Priority
DE 9319473 U 19931217

Abstract (en)
Hybrid switching arrangement has a resistance layer applied on one side of plate-like substrate made of glass or ceramic. A ceramic strip (6) is applied on one side of the substrate (1). Pref. the ceramic strip (6) is made of aluminium oxide, beryllium oxide or aluminium nitride, and is secured using heat conducting adhesive. The substrate (1) and strip (6) are both made of aluminium oxide and are both 1mm thick. The ceramic strip is at most 0.5 (pref. 0.1)mm thick.

Abstract (de)
Auf mindestens einer Seite des plattenförmigen Schaltungsträgers (1) aus Glas oder Keramik ist ein Keramikstreifen (6) von mindestens nahezu gleich großer Fläche in gut wärmeleitender Weise befestigt. <IMAGE>

IPC 1-7
H01C 1/084

IPC 8 full level
H01C 1/01 (2006.01); **H01C 1/084** (2006.01); **H01C 1/144** (2006.01); **H01L 23/498** (2006.01)

CPC (source: EP US)
H01C 1/01 (2013.01 - EP US); **H01C 1/084** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

C-Set (source: EP US)
H01L 2924/0002 + **H01L 2924/00**

Cited by
US5914648A; US6253446B1

Designated contracting state (EPC)
AT CH DE FR GB IT LI SE

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US 5581227 A 19961203; AT E191581 T1 20000415; DE 59409274 D1 20000511; DE 9319473 U1 19940623; EP 0665560 A2 19950802; EP 0665560 A3 19970502; EP 0665560 B1 20000405

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